Approval Sheet for	Product Specification
Customer:	
Product: Epoxy Molding SMD Y2-0	cap
PART No.:	
Mfr. P/N:	
Date: 年 月 日	
Manufacturer	Customer Confirm

Manufacturer		Customer	Confirm
Prepared by	薛志豪	合格 OK □ 不合格 NG □	
Checked by	于金龙	Checked by	
Approved by	范垂旭	Approved by	

Address: No. 177 Xingsheng Road Tiexi District Anshan, China

Tel.: 86-412-8234566 Fax: 86-412-8200366

E-mail: asaec111@126.com



	PART No.	
From Molding CMD V9-con	Edition	Page
Epoxy Molding SMD Y2-cap	Α	2

目录 Index

No.	Item	Page
1	Index	
2	Revision History	
3	Features	
4	Application	
5	Part Number Designation	
6	Appearance and Dimension	
7	Marking、Safety Certification、Structure	
8	Capacity—Temperature curve, capacity, dielectric loss—frequency	
	curve	
9	Specification and Test Method	
10	Package Description	
11	Label	
12	Recommended Soldering Condition	
13	Caution	



			PART No.	
Epoxy Molding SMD Y2-cap		D V2-222	Edition	Page
Ероху	Moraing SM		Α	3
		Revision History		
Edition	Date	Contents of formulation / modification / repeal	Formulation	Approval
Α		New edition released	薛志豪	于金龙



	PART No.	
France Malding CMD V2-car	Edition	Page
Epoxy Molding SMD Y2-cap	Α	4

■ Features

- 1. We design capacitors much more compact in thickness than traditional radial Type, having reduced the thickness to 2.5mm height.
- 2. Operating temperature range guaranteed up to 125 degrees C.
- 3. Dielectric strength: AC2500V
- 4. Class X1/Y2 capacitors certified by UL/ VDE /ENEC
- 5. Coated with flame retardant epoxy resin (conforming to UL94V 0 standard). We recommend a halogen free & beryllium free product* as our standard item.
 - * CI =900ppm max., Br=900ppm max. and Cl+Br=1500ppm max.
- 6. Taping available for automatic SMT reflow.
- 7. AC250V Rated Voltage item is available.
- 8. This one is MSL 3 product. So, in order to avoid the absorption of moisture, capacitors are packed in moisture-proof envelope.

Store the capacitors in the following conditions at all times, and use within 6 months after delivered.

Temperature:10 to 30°C

Humidity: 60%max.

Solder the enclosed capacitors within 168 hours after opening the moisture-proof package. After opening, store the capacitors in moisture-proof package with a desiccant and HIC card and keep the above condition.

In case the storage period has been exceeded 6 months or the indicator color of a enclosed HIC card has changed when the package has been opened, perform baking $(60^{\circ}\text{C}x168\text{hr})$ before soldering.

9. When the product is unpacked, the exposure time exceeds Floor time, the temperature and humidity around the product exceed the requirement. Reference condition for drying mounted or unmounted SMD packages (user bake: Floor life begins at time=0 after bake)

Level	Bake@40°C ≤5%RH	
	Saturated@30°C/85%RH	At limit of Floor life+72hr@30°C/60RH
3	79days	67days

■ Application

- 1. Ideal for use as X/Y capacitors for AC line filters and primary-secondary coupling on switching power supplies and AC adapters.
- 2. Ideal for use on D-A isolation and noise absorption for DAA modems without transformers.
- 3. Mounting Capacitor on both sides of PCB, increasing the space utilization ratio.

■ Part Number Designation

CT7 -250VAC - Y2 - B - 101 K I S

(1) ② ③ ④ ⑤ ⑥ ⑦ ⑧



	PART No.	
Enoug Molding CMD VO con	Edition	Page
Epoxy Molding SMD Y2-cap	Α	5

①Type

Code	Type Designation
CT7	Safety Standard Certified

②Rated Voltage

Code	Rated Vol. (AC)
250VAC	250V

3Class Code

Code	Class Code
Y2	Y2

4Temperature Characteristic

GB	EIA	Temp. range	Cap. Change
S	SL	+25∼+85℃	+350∼−1000ppm/°C
В	Y5P	-25∼+85℃	±10%
Е	Y5U	-25 ∼+85℃	−56%∼+22%

⑤Capacitance

Code	Capacitance
101	100 pF
102	1000 pF

6Tolerance

Code	Tolerance		
K ±10%			
М	\pm 20%		

Shaping method

Description
In-kink
Out-kink

®Lead Shape

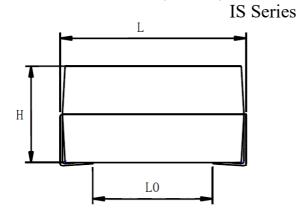
Code	Shape
S	SMD Type

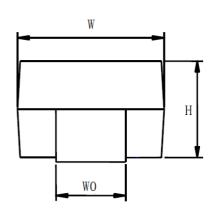
Part No. CODE NO.		STYLE
	CT7-250VAC-Y2-SL-22J IS/OS	
CT7-250VAC-Y2-SL-47J IS/OS		
CT7-250VAC-Y2-B-101K IS/OS		
CT7-250VAC-Y2-B-221K IS/OS		
CT7-250VAC-Y2-B-331K IS/OS		
CT7-250VAC-Y2-B-471K IS/OS		
CT7-250VAC-Y2-E-102M IS/OS		



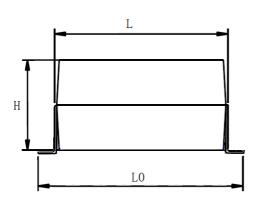
	PART No.	
Engres Molding CMD V9 con	Edition	Page
Epoxy Molding SMD Y2-cap	Α	6

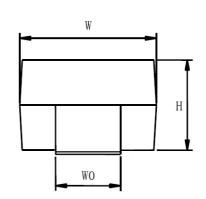
Appearance and Dimension (Unit: mm)





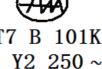
OS Series





Shaping method	L	W	Н	L0	W0
IS	6.2±0.3	5.2±0.3	2.40±0.15	4.2±0.3	2.5±0.2
os	6.2±0.3	5.2±0.3	2.40±0.15	8.4±0.3	2.5±0.2

Marking



CT7 B 101K P Y2 250 ~ 03B2

	-
(F)	Manufacturer's Marking
CT7	Type Designation
В	Temperature Characteristic
101	Nominal Capacitance
K	Capacitance Tolerance
P	Pb solder product
Y2	Class code
250~	Rated Voltage Mark
03B2	Manufactured Date Code (0: Year, 3: Month, B:
	Date, 1: Sequence code)



	PART No.	
Frank Malding CMD V2-car	Edition	Page
Epoxy Molding SMD Y2-cap	Α	7

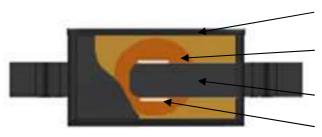
■ Safety Certification

No	Certificate authority	Certificate No	Rated voltage
1	ENEC	40043423	400VAC-Y1/X1,250VAC-Y1/Y2/X1
2	VDE	40043423	400VAC-Y1/X1,250VAC-Y1/Y2/X1
3	UL	E232980	400VAC-Y1/X1,250VAC-Y1/Y2/X1

■ Exemption Clause

2010/571/EU 7(a): Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

■ Structure



包封层 Coating: 环氧树脂 Epoxy Resin

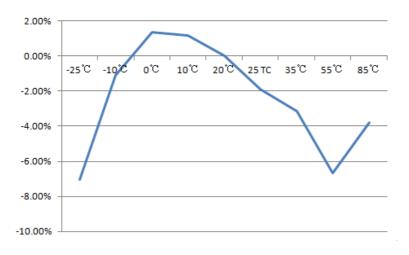
陶瓷介质 Dielectric: 铜电极芯片 Ceramic Chip

with copper electrode

引脚 Lead: 合金 Alloy

焊料 Solder: 锡铅焊料 Sn-Pb

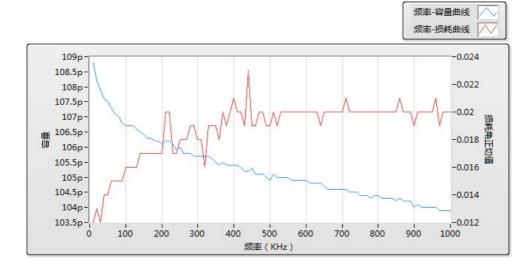
■ Temperature Characteristic Curve





	PART No.	
Energy Molding CMD VO con	Edition	Page
Epoxy Molding SMD Y2-cap	Α	8

■ Cap. & D.F.—Fre. Curve





			at Electronic		PART No.		
Epoxy 1	Molding S	MD Y2-cap	<u> </u>		Edition A	Page 9	
	Specification a	and Test Meth				,	
_	em		pecifications		Test Method		
1 Operating T		-40°C∼+125			Test Metri	ou	
2 Appearance			r abnormalities	Visual inspection	on.		
3 Dimensions			ecified dimensions		neasured by caliper		
4 Marking		To be easily l			should be visually in		
5 Capacitan	Ce	In specified to		Temp. 20°C ±2	-	ispected.	
- Capacitan		Char.	Specifications	Vol. AC 5Vrm			
		SL	<0.15%		1MHz ,B、E:1±0).1KHz.	
6 Dissipation	Factor(D.F.)/Q	B, E	≤2.5%			r should be measured at	
			₹2.0%			1±0.1MHz) and AC	
				5Vrms Max.			
7 Insulation R	7 Insulation Resistance (I.R.) 10000M Ω min		$500\pm50 V$ within 60 ± 5 sec. of charging. The voltage should be applied to the capacitor through a resistor of $1M\Omega$.				
	Between	No failure	Leakage current	The capacitor should not be damaged when the test voltages from Table 1 are applied between the lead wi 60 sec.			
	Lead Wires	SL、B、E	1.0mA max.		Туре	Test Voltage	
				<table 1=""></table>	X1Y1	AC4000V(rms)	
					X1Y2	AC2500V(rms)	
8 Dielectric Strength	Body Insulation	No failure		First, the terminals of the capacitor should be connected together, and the capacitor should be wrapped closely wi an aluminum film around the body of the capacitor to a distance about 2 to 3mm from each terminal. Then, put to capacitor into the testing jig as shown in below figure. Finally, apply a voltage of Table 2 for 60 sec. Plastic insulation Type Test Voltage		be wrapped closely with of the capacitor to a h terminal. Then, put the own in below figure. for 60 sec. insulation inum film	

X1Y2

AC2500V(r.m.s.)



						PART 1	110.		
Frovy Mo	lding SMD	V2-ca	ın.			Edition			Page
Броху мо	Turing Simb	12 Ca	.p			Α			10
Ite	em		Specifications		Т	est Met	hod		
9 Temperature C	haracteristic	Char.	Capacitance Change +350~-1000ppm/℃ (+20℃~+85℃)	The capacitance table.	should 1	be meas	ured at	each ste	ep as belov
		В	±10%	Temp.(°C)	20±2	-25±2	20±2	85±2	20±2
		E							<u> </u>
10 Vibration Resistance	Appearance	No marl	ked defect	Solder the capaci (glass epoxy board) The capacitor shou simple harmonic moamplitude of 1.5mm the approximate lim to 55Hz and return 1 min.This motion sl mutually perpendice	otion have to the sulption have the the free to 10Hz to 10Hz	bjected to ving a tota quency be O to 55Hz. c, should b applied fo	a a sing varied the frequency of a period	uency rar ed in app d of 2hrs	nge, from 10 proximately
-			the terminations are to be d evenly and ously.	Immerse the capacitor in a solution of ethanol (JIS-K-810 rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in solder solution for 2 ± 0.5 sec. Immersing speed: 25 ± 2.5 mm/s Temp. of solder: 245 ± 5 °C Lead Free Solder (Sn-3.0Ag-0.					
12 Deflection		No mark	Dimension(mm) b c d 11.7 2.7 1.0	Solder the capacitor to the test jig(glass epoxy board)shown in Fig. 1. The solder should be done using reflow method and should be conducted to care so that the soldering is uniform a free of defects such as a shock. 20 50 Pressurizing speed: 1.0mm/s Pressurize Capacitance meter 45 Fig.1			he solderin		



	PART No.	
Engrey Molding CMD V9 con	Edition	Page
Epoxy Molding SMD Y2-cap	A	11

1 3		Α	11					
Ite	m		Specifications		Test Method			
13 Adhesive St Termination	trength of	No removal of the terminations or other defect should occur.		Solder the capacitor to the test jig(glass epoxy board)show in Fig.2 Then apply 10N force in the direction of the arrow. T soldering should be done using reflow method and should conducted with care so that the soldering is uniform and fr of defects such as heat shock. Fig. 2				
	Appearance	No marked defect		Preheat the capa	citor as in			
	Capacitance				260±5℃for	Molten Solder		
14 Resistance	Change	В	±10%	condition for 24 ±	ion for $24\!\pm\!2$ hrs., then measured.			
to		E	±15%	Immersing speed: 25 ± 2.5 mm/s				
Soldering	I.R.	1000M Ω π	nin	Pretreatment for Y5P \times Y5U char. Perform a heat treatment at 150^{+0}_{-10} °C for 60 ± 5 min. and				
Heat	Dielectric Strength	Per Item 8.			Temperature 100 to 120°C 170 to 200°C			
	Appearance	No marked	defect	Before this tes	t, the test shown in	the following is		
15 稳态湿热 Humidity	Capacitance Change	Char. SL B E	Capacitance Change ±5% or ±0.5pF (whichever is larger) ±10% ±15%	 performed. Item 12 Deflection Item 13 Adhesive Strength of Termination (applied force is 5N) Set the capacitor for 500 ⁺²⁴₋₀ hrs. at 40±2°C in 90 to 95% relative humidity . Pretreatment for Y5P、Y5U char. Perform a heat treatment at 150 ⁺⁰₋₁₀ °C for 60±5 min. and then let sit for 24±2 hrs. at room condition. 				
(under Steady State)	D.F./Q	Char. SL B、E	Specifications ≤0.3% ≤5.0%					
	I.R.	3000MΩ m	nin	Post-treatment:	The capacitor should be	stored for 1 to 2		
	Dielectric Strength	Per Item 8.		hours at room co	ndition.			



	PART No.	
Engres Molding CMD V9 con	Edition	Page
Epoxy Molding SMD Y2-cap	A	12

				А	12			
Ite	Item		pecifications	Test Method				
16 Humidity	Appearance	No	marked defect	Before this test,	the test shown i	n the following is		
Loading	Capacitance	Char.	Capacitance Change	performed.				
	Change	SL	±5% or ±0.5pF	 Item 12 Deflection Item 13 Adhesive Strength of Termination (applied fo is 5N) 				
			(whichever is larger)					
		В	±10%	· ·	Itage for 500 ⁺²⁴ ₋₀ hrs. a	ut 40 ± 2°C in 90% to		
		E	±15%	95% relative humid		10 40 11 00% 10		
	D.F./Q	Char.	Specifications	Pretreatment for `	-			
		SL	≤0.3%	Perform a heat tro	eatment at 150 $^{+0}_{-10}{}^{\circ}\!{ m C}$	for 60±5 min. and		
		B _v E	≤5.0%		±2 hrs. at room cond			
	I.R.	;	3000 MΩ min	Post-treatment:				
	Dielectric		Per Item 8.	Capacitor should	be stored for 24	\pm 2 hrs. at room		
	Strength			condition				
	Appearance	No	marked defect	Before this test,	the test shown i	n the following is		
		Char.	Capacitance Change	performed.				
	Capacitance	SL	±5% or ±1.0pF	Item 12 Deflect	• Item 12 Deflection			
	Change		(whichever is larger)	• Item 13 Adhesive Strength of Termination (appli	ation (applied force			
		B、E	±20%	is 5N)				
	I.R.	3000MΩ n	nin	Impulse voltage				
				Each individual cap	pacitor should be sub	jected to a 5KV		
				(X1Y2) / 8KV (X1Y	Y1) impulse for three	times. Then the		
				capacitors are app	olied to life test.			
				100 (%)	T ₁ =1.2μS=1.0 T ₂ =50μS	57T		
47				50	12-30μ3			
17 Life				30				
				T T T T T T T T T T	→ 			
	Dielectric		_		170% of rated voltage	-		
	Strength	Per Item	8.	each hour the voltage is increased to AC1000V (r.m.s.) for				
				0.1sec for 1000 hrs., at 125 $^{+2}_{-0}$ °C and relative humidity of		elative numidity of		
				50% max. Pretreatment for `	VSD VSII obor			
					eatment at 150^{+0}_{-10} °C $^{\circ}$	for 60±5 min and		
					±2 hrs. at room cond			
				Post-treatment:		indort.		
					Post-treatment: Capacitors should be stored for 24±2 hrs at room			
				condition.	25 500104 101 24 12			
	l	I		Jonata of It				



	PART No.	
France Molding CMD V2-con	Edition	Page
Epoxy Molding SMD Y2-cap	Α	13

Epoxy Moraring SMD	12 Cap		Α	13
Item	Specifications		Test Method	
18 Passive Flammability	The burning time should not exceed 30 sec. The tissue paper should not ignite.	position that best only be exposed o flame: 30 sec. Length of flame: 1 Gas burner: Leng Insid	gth 35mm min. le Dia. 0.5±0.1mm side Dia. 0.9mm max.	ch specimen should e of exposure to
19 Active Flammability	The cheesecloth should not be on fire.	least one but not cheesecloth. The 20 discharges. T discharges shoul maintained for 2 $C_{1,2}:1\mu F\pm 10\%$	ander test $U_{AC}: U_{AC}: U$	mplete layers of one subjected to a successive consuld be discharge. The consult be discharge.



			PART No.	
E W. 1 L CND VO			Edition	Page
Epoxy Molding SMD Y2-cap		Α	14	
•				

Appearance	Sp	ecifications			T4 M -41		
Appearance		Specifications		Test Method			
	No marked defect		The capacitor should be subjected to 5 temperature				
	Char. Capacitance Change			cycles, then consecutively to 2 immersion cycles.			
		±5% or ±1.0pF			< Temperature (Cycle>	
-	SL (whichever is larger)		C.	T (°C)	T' (:)		
Change	В	±10%		-	1 /	Time(min)	
	E	±20%	-	2	Room temp.	3	
	Char.	Specifications]	3	125+3/-0	30	
).F./Q				4	Room temp.	3	
, <u>-</u>		<u> </u>			Cycle time:5 cycl	es	
R.	<u> </u>		<pre></pre>			le>	
1.0	SOOOW S2 IIIIII		Step	Temp.(°C) Time(min)	Immersion Water	
			1	65+5/-	-0 15	Clean water	
			2 0±3 1		3 15	Salt water	
			Cycle time:2 cycles				
			Pre-treatment:				
			Capacitor should be stored at 85±2° C for 1 hr., then,				
Dielectric			placed at room condition for 24±2 hrs.			hrs.	
Strength	Per Item 8.		Pretrea	tment fo	r Y5P、Y5U char.		
			Perform a heat treatment at 150^{+0}_{-10} °C for 60 ± 5 min. an			°C for 60±5 min. and	
			then let sit for 24±2 hrs. at room condition.				
			Capacit	or should	d be stored for 24±	:2 hrs. , at room	
						·	
D. F	ર. ielectric	B E Char. SL B \ E R. 3000M Ω missible lielectric Per Item 8.	apacitance hange $ \begin{array}{c c} SL & \text{(whichever is larger)} \\ \hline B & \pm 10\% \\ \hline E & \pm 20\% \\ \hline \\ Char. & Specifications \\ \hline SL & \leqslant 0.3\% \\ \hline B \ E & \leqslant 5.0\% \\ \hline R. & 3000M \Omega \ \text{min} \\ \hline \\ ielectric & Per Item 8. \\ \hline \end{array} $	apacitance hange $ \begin{array}{ c c c c }\hline & SL & & & & \\ \hline & B & & \pm 10\% & \\ \hline & E & & \pm 20\% & \\ \hline & .F./Q & & & \\ \hline & .F./Q & & & \\ \hline & .SL & & & \\ \hline$	Step	apacitance hange $ \begin{array}{ c c c c }\hline B & \pm 10\% \\ \hline B & \pm 20\% \\ \hline E & \pm 20\% \\ \hline \hline SL & \leq 0.3\% \\ \hline B & E & \leq 5.0\% \\ \hline R. & 3000M \Omega & min \\ \hline \end{array} $	



	PART No.	
Energy Molding CMD VO con	Edition	Page
Epoxy Molding SMD Y2-cap	A	15

■ Package

Paste product label and moisture-sensitive warning label on the taping reel, then, take the reel, HIC card and desiccant(30g) into the package bag, vacuum sealed.

Product Label



No.	Description	No.	Description
1	Code Number	5	Remark
2	ITEM	6	Check
3	SPEC	7	Produce Date
4	Quantity	8	Batch

Package style and moisture-sensitive warning label Label



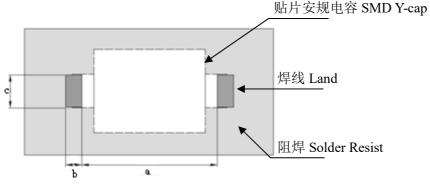
警告:虚度蒙惠产品 Caution:moisture-sensitive devices Level 3					
储存条件 Storage Condition	Temperature:10 to 30°C Humidity: 60%max.				
使用期限 Using Period	6个月 6months				
打开包装后使用条件 Using Condition after opening	打开包装后室内环境30℃/60%RH,168小时内回流焊接 末使用产品附干燥剂和HIC卡密封包装储存 Mounted & Reflow within 168hr of factory condition ≤30℃/60%RH Stored in moisture-proof package with a desiccant and HIC card				
后处理 Post-treatment	如果超过6个月的储存期,或包装打开后随附的HIC 卡的指示颜色发生变化,则应在焊接前进行烘烤 (60℃x168hr)。 In case the storage period has been exceeded 6 months or the color of HIC card has changed, perform baking (60℃x168hr)before soldering.				



	PART No.	
Frank Malding CMD V2-car	Edition	Page
Epoxy Molding SMD Y2-cap	A	16

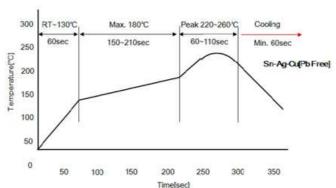
■ Recommended Soldering Condition

1. Soldering Land Pattern Size



Shaping method	а	b	С
IS	4.2 ± 0.3 mm	0.9 ± 0.1 mm	2.6±0.1mm
os	8.4 ± 0.3 mm	0.9 ± 0.1 mm	2.6 ± 0.1 mm

2. Reflow Soldering Temperature Profile



	Zone	Temp. range (℃)	Time(sec)	Remark
а	Curing	RT~130	60	
b	Preheat	180 max	150~210	Solder: Sn-Ag-Cu
С	Soldering	220~260(260 max)	60~110	Peak time: less than 10 sec
d	Cooling	220~RT	60 min	

Solder ability of tin plating termination pins might be deteriorated when a low temperature soldering profile where the peak solder temperature is below the melting point of tin is used. Please confirm the solder ability of tin plated termination pins before use

The maximum temperature in the air outlet and the space of Reflow soldering is 280°C max., if the temperature exceed, it maybe a failure occur. Our company will not be held responsible for any adverse effects caused by over temperature using

■ Caution (Rating)

1. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the V p-p value of the applied voltage or the Vo-p that contains DC bias within the rated voltage range.



	PART No.	
From Molding CMD V9-000	Edition	Page
Epoxy Molding SMD Y2-cap	A	17

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage	Pulse Voltage (1)	Pulse Voltage (2)
Positional Measurement	Vo-p	Vo-p	V _D -p	V _D -p	Vp-p

2. Operating Temperature and Self-generated Heat (Apply to B/E Char.)

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high-frequency current, pulse current or similar current, it may have self-generated heat due to dielectric loss. Applied voltage load should be such that self-generated heat is within 20° C under the condition where the capacitor is subjected to an atmospheric temperature of 25° C. When measuring, use a thermocouple of small thermal capacity-K of Φ 0.1mm under conditions where the capacitor is not affected by radiant heat from other components or wind from surroundings. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

3. Test Condition for Withstanding Voltage

(1) Test Equipment

Test equipment for AC withstanding voltage should be used with the performance of the wave similar to 50/60Hz sine wave.

If the distorted sine wave or overload exceeding the specified voltage value is applied, a defect may be caused.

(2) Voltage Applied Method

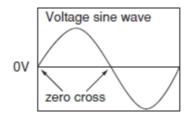
When the withstanding voltage is applied, the capacitor's lead or terminal should be firmly connected to the output of the withstanding voltage test equipment, and then the voltage should be raised from near zero to the test voltage.

If the test voltage without the raise from near zero voltage would be applied directly to capacitor, test voltage should be applied with the zero cross.* At the end of the test time, the test voltage should be reduced to near zero, and then capacitor's lead or terminal should be taken off the output of the withstanding voltage test equipment. If the test voltage without the raise from near zero voltage would be applied directly to capacitor, the surge voltage may rise, and therefore, a defect may be caused.



	PART No.	
From Molding CMD V2-con	Edition	Page
Epoxy Molding SMD Y2-cap	A	18

*ZERO CROSS is the point where voltage sine wave passes 0V. See the figure at below.



4. Fail-Safe

When the capacitor is broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure could result in an electric shock, fire or fuming.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

Caution (Storage and Operating Condition)

The insulating Epoxy molded capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect produce quality by testing the performance of a cleaned, bonded or molded product in the intended equipment.

This one is MSL 3 product. So, in order to avoid the absorption of moisture, capacitors are packed in moisture-proof envelope.

Store the capacitors in the following conditions at all times, and use within 6 months after delivered.

Temperature:10 to 30°C

Humidity: 60%max.

Solder the enclosed capacitors within 168 hours after opening the moisture-proof package. After opening, store the capacitors in moisture-proof package with a desiccant and HIC card and keep the above condition.

In case the storage period has been exceeded 6 months or the indicator color of a enclosed HIC card has changed when the package has been opened, perform baking (60°C x168hr) before soldering.

When the product is unpacked, the exposure time exceeds Floor time, the temperature and humidity around the product exceed the requirement. Reference condition for drying mounted or unmounted SMD packages (user bake: Floor life begins at time=0 after bake)



	PART No.	
From Molding CMD V2-con	Edition	Page
Epoxy Molding SMD Y2-cap	A	19

Level	Bake@40°C ≤5%RH	
	Saturated@30°C/85%RH	At limit of Floor life+72hr@30°C/60RH
3	79days	67days

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHOCT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

Caution (Soldering, Mounting and Handing)

1. Vibration and Impact

Do not expose a capacitor or its pins to excessive shock or vibration during use.

Excessive shock or vibration may cause fatigue destruction of lead wires mounted on the circuit board.

Please take measures to hold a capacitor on the circuit boards by adhesive, molding resin or another coating.

Please confirm there is no influence of holding measures on the product with the intended equipment.

2. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specifications of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

Soldering the capacitor with a soldering iron should be performed in the following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage: 50W max.

Soldering time: 3.5 sec. max.

3. Bonding, Resin Molding and Coating

Before bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case the amount of applications, dryness/hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive, molding resin or coating may cause outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

4. Treatment after Bonding, Resin Molding and Coating

When the outer coating is hot (over 100 degrees C.) after soldering, it becomes soft and fragile. Therefore, please be careful not to give it mechanical stress.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHOCT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.



	PART No.	
Energy Molding CMD VO com	Edition	Page
Epoxy Molding SMD Y2-cap	Α	20

Notice (Soldering and Mounting)

Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less. Rinsing time: 5 min. max.

Do not vibrate the PCB/PWB directly. Excessive ultrasonic cleaning may lead to fatigue destruction of the pins.

Notice (Rating)

- 1. Capacitance Change of Capacitors
- (1) For CH/SL/DL char.

Capacitance might change a little depending on a surrounding temperature or an applied voltage.

Please contact us if you use a strict constant time circuit.

(2) For B/E char.

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage. Therefore, it is not likely to be suitable for use in a constant time circuit.

Please contact us if you need detailed information.

2. Performance Check by Equipment

Before using a capacitor, check that there is no problem in the equipment's performance and the specifications.

Generally speaking, CLASS 2 (B/E char.) ceramic capacitors have voltage dependence characteristics and temperature dependence characteristics in capacitance, so the capacitance value may change depending on the operating condition in the equipment. Therefore, be sure to confirm the apparatus performance of receiving influence in the capacitance value change of a capacitor, such as leakage current and noise suppression characteristic.

Moreover, check the surge-proof ability of a capacitor in the equipment, if needed, because the surge voltage may exceed specific value by the inductance of the circuit.